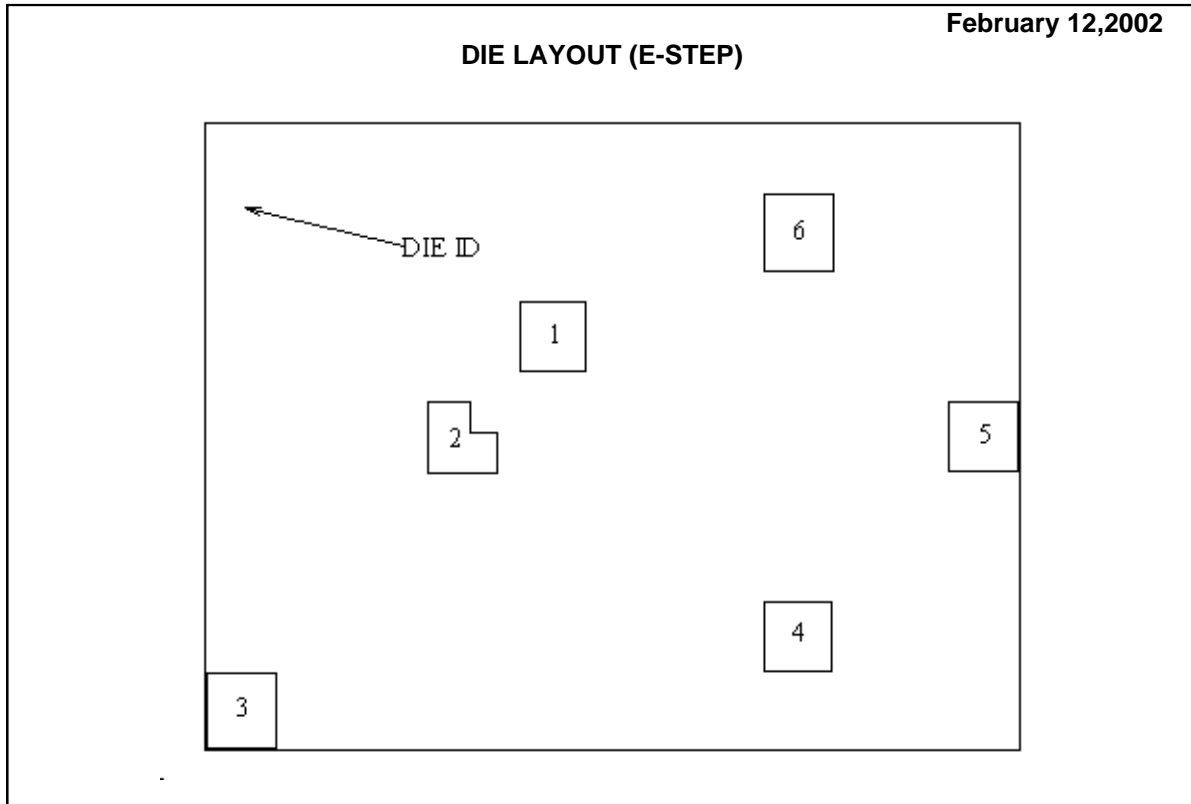


**LM120KG-5 MD8 MW8
SERIES 3-TERMINAL NEGATIVE REGULATORS**



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	120E	Bond Pad Opening Size (min)	183 μ m x 193 μ m
Die Step	E	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM
Wafer Diameter	100mm	Back Side Metal	Gold
Die Size (Drawn)	1753 μ m x 2261 μ m 69mils x 89mils	Back Side Connection	INPUT
Thickness	254 μ m Nominal		
Min Pitch	768 μ m Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

LM120KG-5 MD8 MW8

SERIES 3-TERMINAL NEGATIVE REGULATORS

Die Bond Pad Coordinate Locations (E -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
OUTPUT	1	-178	279	183	x	193
NC	2	-433	-1	191	x	201
GND	3	-1054	-768	193	x	206
INPUT	4	507	-558	191	x	194
OUTPUT	5	1029	0	193	x	193
INPUT	6	508	570	193	x	216

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